



# SF206C Low Dk/Df 聚酰亚胺薄膜覆盖膜

SF206C Low Dk/Df Polyimide Film Based Coverlay

## 特点

- 低介电常数，低传输损耗
- 优秀的耐热性、耐化学性和电性能
- 不含卤素，阻燃性达到 UL94 V-0 .
- 加工性好，适于快速压合和传统压合
- 满足 RoHS 指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

## FEATURES

- Low dielectric constant, low dissipation loss.
- Excellent thermal resistance ,chemical resistance and electrical property
- Halogen free, Flammability UL94 V-0.
- Good processability, suitable for both fast and traditional lamination style
- Compatible with EU RoHS directive, free of Pb,Hg,Cd, Cr<sup>6+</sup>,PBB,PBDE, etc..

## 性能表 GENERAL PROPERTIES

性能项目 Test Item	测试方法 Test Method	单位 Unit	IPC 标准值* Standard	典型值 Typical Value
				SF206C 0515
溢胶量 Resin Flow	SY Method	mm	-	<0.15
剥离强度 Peel Strength (90°)	IPC-TM-650,No.2.4.9	N/mm	≥0.8	0.92
	Method A		≥0.8	0.92
	Method C			
热应力 Thermal Stress	IPC-TM-650,No.2.4.13	-	Pass	Pass
尺寸稳定性 Dimensional Stability	SY Method	%	±0.2	MD: -0.0223 TD: -0.0393
耐化学性 Chemical Resistance	IPC-TM-650,No.2.3.2	%	≥80	>85
吸水率 Moisture Absorption	IPC-TM-650,No.2.6.2	%	≤3	0.53
电气强度 Dielectric strength	IPC-TM-650,No.2.5.6.2	KV/mm	≥80	110.4
介电常数 10GHz Dielectric Constant	IEC-61189-2-721	-	≤3.5	3.11
介电损耗 10GHz Dissipation Factor	IEC-61189-2-721	-	≤0.02	0.0091
介电常数 10GHz Dielectric Constant	IEC-61189-2-721	-		2.56(胶层)
介电损耗 10GHz Dissipation Factor	IEC-61189-2-721	-	-	0.0025 (胶层)

## 应用领域

高频印制板和刚挠性印制板。

## APPLICATIONS

Be used in high frequency FPC and rigid-flex PCB.



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## 产品规格代码描述 Product Code Description

SF206C 05 15

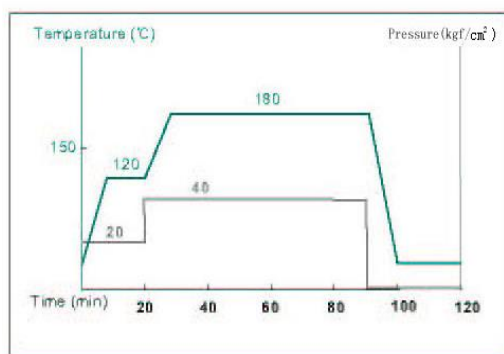
- 胶粘剂厚度 Adhesive Thickness: 15- 15  $\mu$  m; 25 - 25  $\mu$  m
- PI 膜厚度 PI film Thickness: 05 – 12.5  $\mu$  m
- 生益覆盖膜产品编号 Shengyi Coverlay Designation

## 常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS

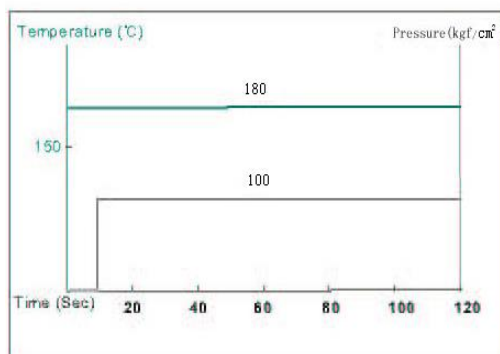
产品规格 Specifications	PI 膜厚度 ( $\mu$ m) PI film Thickness	胶粘剂厚度 ( $\mu$ m) Adhesive Thickness	应用领域 Applications
SF206C 0515	12.5	15	高频印制板和刚挠 性印制板 high frequency FPC and rigid-flex PCB
SF206C 0520	12.5	20	
SF206C 0525	12.5	25	
SF206C 1025	25	25	
SF206C 1030	25	30	

## 压板推荐 PRESS PROPOSE

### HOT PRESSING CYCLE



### FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整；采用快压方式，后固化条件氮气烘烤，160-180 $^{\circ}$ C、60-90分钟。

The parameters of hot pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-180 $^{\circ}$ C for 60-90min in N<sub>2</sub> condition.

## 包装 PURCHASING INFORMATION

产品宽度250+2/-0mm或500+2/-0mm，每卷100+2/-0米或200+2/-0米；其它规格、尺寸可根据客户要求而定。SF206C is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

## 贮存条件 STORAGE CONDITION

贮存在干燥、无腐蚀气体的室内。以原始包装贮存在4-10 $^{\circ}$ C的冷藏室里，贮存期为三个月。

Stored in dry room with humidity control and with no corrosive gases. Three months when stored in the original packaging at 4-10 $^{\circ}$ C.